

**In the Claims:**

This listing of claims replaces all prior versions, and listings, of claims in the application.

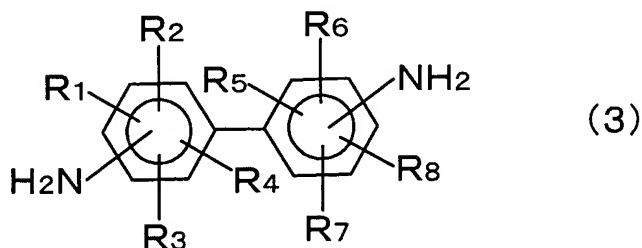
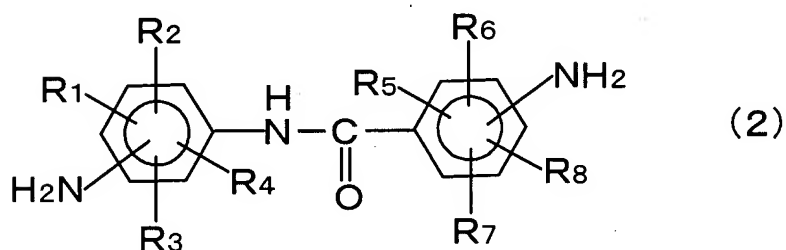
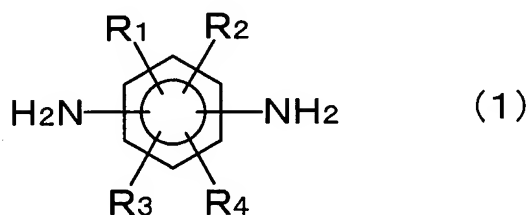
1. (Currently Amended) A heat-resistant resin laminate film comprising a heat-resistant insulating film, and ~~[[a]]~~ at least one heat-resistant resin ~~layer(s)~~ layer laminated on at least one surface of said heat-resistant insulating film, said heat-resistant resin layer having a coefficient of linear expansion  $k_A$  (ppm/ $^{\circ}$ C) within the range of  $k-10 \leq k_A \leq k+20$ , ~~[[()]]~~ wherein  $k$  represents the coefficient of linear expansion of said heat-resistant insulating film~~[[D]]~~.

2. (Currently Amended) The heat-resistant resin laminate film according to claim 1, ~~comprising a heat-resistant insulating film, and a heat-resistant resin layer(s) laminated on at least one surface of said heat-resistant insulating film,~~ wherein said heat-resistant resin layer comprises not less than two heat-resistant resin layers at least one of which has a coefficient of linear expansion  $k_A$  (ppm/ $^{\circ}$ C) within the range of  $k-10 \leq k_A \leq k+20$  ~~(wherein  $k$  represents the coefficient of linear expansion of said heat-resistant insulating film).~~

3. (Currently Amended) The heat-resistant resin laminate film according to claim 1 ~~or 2~~, wherein said heat-resistant insulating film has a coefficient of linear expansion of 5 to 25 ppm/ $^{\circ}$ C, and said heat-resistant resin layer having the coefficient of linear expansion  $k_A$  (ppm/ $^{\circ}$ C) within the range of  $k-10 \leq k_A \leq k+20$  ~~(wherein  $k$  represents the coefficient of linear expansion of said heat-resistant insulating film)~~ has a coefficient of linear expansion of 5 to 30 ppm/ $^{\circ}$ C.

4. (Currently Amended) The heat-resistant resin laminate film according to ~~any one of claims 1 to 3~~ claim 1, wherein the resin constituting said heat-resistant resin layer having the coefficient of linear expansion  $k_A$  (ppm/ $^{\circ}$ C) within the range of  $k-10 \leq k_A \leq k+20$  ~~(wherein  $k$  represents the coefficient of linear expansion of said heat-~~

~~resistant insulating film~~) is a polyimide resin comprising as a diamine ~~component(s)~~ component at least one aromatic diamine represented by any of the Formulae (1) to (3) in an amount of not less than 40 mol% based on the total diamine ~~component(s)~~ component:



[[(1)]] wherein R<sup>1</sup> to R<sup>8</sup> are the same or different and are selected from the group consisting of hydrogen, C<sub>1</sub>-C<sub>30</sub> alkyl, C<sub>1</sub>-C<sub>30</sub> alkoxy, halogen, hydroxy, carboxyl, sulfonic, nitro and cyano [[(1)]].

5. (Currently Amended) The heat-resistant resin laminate film according to claim 4, wherein said diamine ~~component(s)~~ component of said polyimide resin comprises at least one selected from the group consisting of *p*-phenylenediamine, 4,4'-diaminobenzanilide and 2,2'-dimethylbenzidine, in an amount of not less than 40 mol%

based on the total diamine ~~component(s)~~ component.

6. (Currently Amended) The heat-resistant resin laminate film according to claim 4, wherein a tetracarboxylic acid ~~component(s)~~ component of said polyimide resin ~~comprise~~ comprises pyromellitic dianhydride and/or biphenyltetracarboxylic dianhydride in an amount of not less than 40 mol% based on the total tetracarboxylic acid ~~component(s)~~ component.

7. (Currently Amended) A laminate film having a metal ~~layer(s)~~ layer, comprising said heat-resistant resin laminate film according to ~~any one of claims 1 to 6~~ claim 1, and a metal ~~layer(s)~~ layer laminated on said heat-resistant resin ~~layer(s)~~ layer.

8. (Currently Amended) The laminate film having a metal ~~layer(s)~~ layer according to claim 7, comprising said heat-resistant insulating film and said metal layer(s) laminated on at least one surface of said heat-resistant insulating film through said heat-resistant resin layer, wherein said heat-resistant resin layer comprises at least two layers including said heat-resistant resin layer A whose coefficient of linear expansion  $k_A$  (ppm/ $^{\circ}$ C) is within the range of  $k-10 \leq k_A \leq k+20$ , ~~[[()]]~~ wherein  $k$  represents the coefficient of linear expansion of said heat-resistant insulating film~~[[()]]~~, and a heat-resistant resin layer B having a glass transition temperature lower than that of said heat-resistant resin layer A, said heat-resistant resin layer A being laminated at a side so as to contact said metal layer, and said heat-resistant resin layer B being laminated at a side so as to contact said heat-resistant insulating film.

9. (Original) The laminate film having a metal layer(s) according to claim 8, wherein said heat-resistant resin layer A has a glass transition temperature of 250 $^{\circ}$ C to 400 $^{\circ}$ C.

10. (Currently Amended) The laminate film having a metal ~~layer(s)~~ layer according to claim ~~8 or 9~~, wherein said heat-resistant resin layer A has a thickness of not less than twice that of said heat-resistant resin layer B.

11. (Currently Amended) The laminate film having a metal ~~layer(s)~~ layer according to ~~any one of claims 8 to 10~~ claim 8, wherein said heat-resistant resin layer B consists essentially of ~~[[a]] polyimide resin(s)~~ resin.

12. (Original) The laminate film having a metal layer(s) according to claim 11, wherein said heat-resistant resin layer B has a glass transition temperature of 120°C to 280°C.

13. (Currently Amended) The laminate film having a metal ~~layer(s)~~ layer according to ~~any one of claims 8 to 10~~ claim 8, wherein said heat-resistant resin layer B consists essentially of a thermosetting ~~resin(s)~~ resin containing an epoxy ~~compound(s)~~ compound.

14. (Currently Amended) The laminate film having a metal ~~layer(s)~~ layer according to claim 13, wherein said heat-resistant resin layer B has a glass transition temperature of 50°C to 250°C.

15. (Currently Amended) A semiconductor device comprising said laminate film having a metal ~~layer(s)~~ layer according to ~~any one of claims 6 to 14~~ claim 6.

16. (Currently Amended) A process of producing a laminate film having a metal ~~layer(s)~~ layer comprising a heat-resistant insulating film and a metal ~~layer(s)~~ layer laminated on at least one surface of said heat-resistant insulating film through a heat-resistant resin layer(s) ~~layer(s)~~ layer, said process comprising ~~the steps of~~ laminating at least one heat-resistant resin layer including a heat-resistant resin layer having a coefficient of linear expansion  $k_A$  (ppm/°C) within the range of  $k-10 \leq k_A \leq k+20$ , ~~[[()]]~~ wherein  $k$  represents the coefficient of linear expansion of said heat-resistant insulating film, ~~[[()]]~~ on said metal layer; laminating the resulting metal layer/heat-resistant resin layer ~~laminates(s)~~ laminates and said heat-resistant insulating film ~~which may, as required, have at least one heat-resistant resin layer~~; and heat pressing the resulting laminate.

17. (Currently amended) A process of producing a laminate film having a metal layer(s) ~~layer(s)~~ layer comprising a heat-resistant insulating film and a metal layer(s) ~~layer(s)~~ layer laminated on at least one surface of said heat-resistant insulating film through a heat-resistant resin layer(s) ~~layer(s)~~ layer, said process comprising ~~the steps of~~ laminating at least one heat-resistant resin layer including a heat-resistant resin layer having a coefficient of linear expansion  $k_A$  (ppm/ $^{\circ}$ C) within the range of  $k-10 \leq k_A \leq k+20$ , ~~[[()]]~~ wherein  $k$  represents the coefficient of linear expansion of said heat-resistant insulating film, ~~[[()]]~~ on said heat-resistant insulating film; laminating the resulting heat-resistant insulating film/heat-resistant resin layer laminate and said metal ~~layer(s)~~ layer which may, as required, have at least one heat-resistant resin layer; and heat pressing the resulting laminate.